

VNP10N06

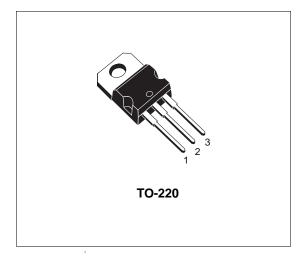
"OMNIFET": FULLY AUTOPROTECTED POWER MOSFET

TYPE	V _{clamp}	R _{DS(on)}	l _{lim}
VNP10N06	60 V	0.3 Ω	10 A

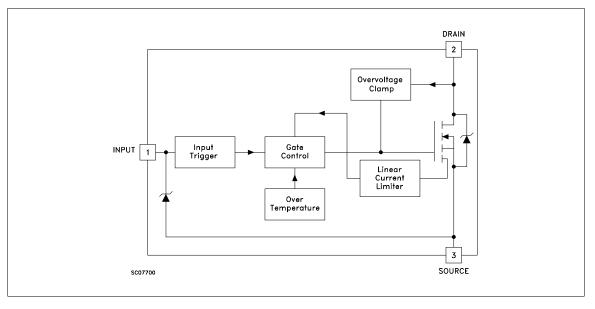
- LINEAR CURRENT LIMITATION
- THERMAL SHUT DOWN
- SHORT CIRCUIT PROTECTION
- INTEGRATED CLAMP
- LOW CURRENT DRAWN FROM INPUT PIN
- LOGIC LEVEL INPUT THRESHOLD
- ESD PROTECTION
- SCHMITT TRIGGER ON INPUT
- HIGH NOISE IMMUNITY
- STANDARD TO-220 PACKAGE

DESCRIPTION

The VNP10N06 is a monolithic device made using STMicroelectronics VIPower Technology, intended for replacement of standard power MOSFETS in DC to 50 KHz applications. Built-in thermal shut-down, linear current limitation and overvoltage clamp protect the chip n harsh enviroments.



BLOCK DIAGRAM



March 2004

VNP10N06

ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{in} = 0)	Internally Clamped	V
Vin	Input Voltage	Internally Clamped	V
l _{in}	Input Current	± 20	mA
ID	Drain Current	Internally Limited	А
IR	Reverse DC Output Current	-15	А
V _{esd}	Electrostatic Discharge (C= 100 pF, R=1.5 KΩ)	4000	V
Ptot	Total Dissipation at $T_c = 25 \ ^{\circ}C$	42	W
Tj	Operating Junction Temperature	Internally Limited	°C
Tc	Case Operating Temperature	Internally Limited	°C
T _{stg}	Storage Temperature	-55 to 150	°C

THERMAL DATA

R _{thj-case}	Thermal Resistance Junction-case	Max	3	°C/W
Rthj-amb	Thermal Resistance Junction-ambient	Max	62.5	°C/W

ELECTRICAL CHARACTERISTICS (T_{case} = 25 o C unless otherwise specified) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Vclamp	Drain-source Clamp Voltage	$I_D = 200 \text{ mA}$ $V_{in} = 0$	50	60	70	V
VIL	Input Low Level Voltage	$I_D = 100 \ \mu A$ $V_{DS} = 16 \ V$			1.5	V
V _{IH}	Input High Level Voltage		3.2			V
VINCL	Input-Source Reverse Clamp Voltage	$I_{in} = -1 \text{ mA}$ $I_{in} = -1 \text{ mA}$	-1 8		-0.3 11	V V
IDSS	Zero Input Voltage Drain Current (V _{in} = 0)	$ \begin{array}{ll} V_{DS} = 50 \ V & V_{in} = V_{IL} \\ V_{DS} < 35 \ V & V_{in} = V_{IL} \end{array} $			250 100	μΑ μΑ
liss	Supply Current from Input Pin	$V_{DS} = 0 V V_{in} = 5 V$		150	300	μA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
R _{DS(on)}	Static Drain-source On Resistance	$V_{in} = 7 V$ $I_D = 1 A T_J < 125 °C$		0.15	0.3	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Coss	Output Capacitance	$V_{DS} = 13 V$ f = 1 MHz $V_{in} = 0$		350	500	pF

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ELECTRICAL CHARACTERISTICS (continued)

SWITCHING (**)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Rise Time			1100 550	1600 900	ns ns
t _{d(off)} t _f	Turn-off Delay Time Fall Time	(see figure 3)		200 100	400 200	ns ns
t _{d(on)} t _r t _{d(off)} t _f	Turn-on Delay Time Rise Time Turn-off Delay Time Fall Time			1.2 1 1.6 1.2	1.8 1.5 2.3 1.8	μs μs μs μs
(di/dt) _{on}	Turn-on Current Slope	$V_{DD} = 16 V$ I _D = 1 A V _{in} = 7 V R _{gen} = 10 Ω		1.5		A/µs
Qi	Total Input Charge	$V_{DD} = 12 \text{ V} I_D = 1 \text{ A} V_{in} = 7 \text{ V}$		13		nC

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{SD} (*)	Forward On Voltage	$I_{SD} = 1 A$ $V_{in} = V_{IL}$		0.8	1.6	V
t _{rr} (**)	Reverse Recovery Time	$I_{SD} = 1 A$ di/dt = 100 A/µs V _{DD} = 30 V $T_i = 25 \ ^{\circ}C$		125		ns
Qrr (**)	Reverse Recovery Charge	(see test circuit, figure 5)		0.22		μC
I _{RRM} (**)	Reverse Recovery Current			3.5		A

PROTECTION

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
l _{lim}	Drain Current Limit	V _{in} = 7 V V _{DS} = 13 V	6	10	15	Α
t _{dlim} (**)	Step Response Current Limit	$V_{in} = 7 V$ V_{DS} step from 0 to 13 V		12	20	μs
T _{jsh} (**)	Overtemperature Shutdown		150			°C
T _{jrs} (**)	Overtemperature Reset		135			°C
E _{as} (**)	Single Pulse Avalanche Energy	starting $T_j = 25 ^{\circ}C V_{DD} = 24 V$ $V_{in} = 7 V R_{gen} = 1 K\Omega L = 10 \text{mH}$	250			mJ

(*) Pulsed: Pulse duration = $300 \,\mu$ s, duty cycle 1.5 % (**) Parameters guaranteed by design/characterization



PROTECTION FEATURES

During Normal Operation, the INPUT pin is electrically connected to the gate of the internal power MOSFET through a low impedance path as soon as $V_{\text{IN}} > V_{\text{IH}}$.

The device then behaves like a standard power MOSFET and can be used as a switch from DC to 50KHz. The only difference from the user's standpoint is that a small DC current (typically 150 μ A) flows into the INPUT pin in order to supply the internal circuitry.

During turn-off of an unclamped inductive load the output voltage is clamped to a safe level by an integrated Zener clamp between DRAIN pin and the gate of the internal Power MOSFET.

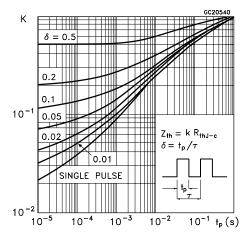
In this condition, the Power MOSFET gate is set

to a voltage high enough to sustain the inductive load current even if the INPUT pin is driven to 0V. The device integrates an active current limiter circuit which limits the drain current I_D to I_{lim} whatever the INPUT pin Voltage.

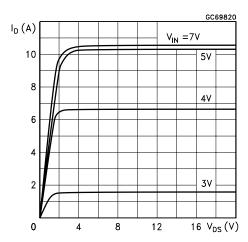
When the current limiter is active, the device operates in the linear region, so power dissipation may exceed the heatsinking capability. Both case and junction temperatures increase, and if this phase lasts long enough, junction temperature may reach the overtemperature threshold T_{jsh} .

If T_j reaches T_{jsh} , the device shuts down whatever the INPUT pin voltage. The device will restart automatically when T_j has cooled down to T_{jrs}

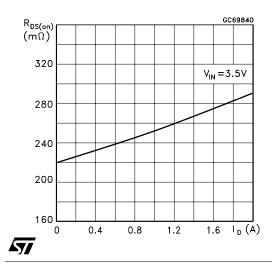
Thermal Impedance



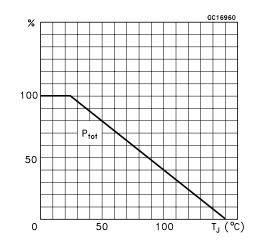
Output Characteristics

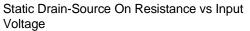


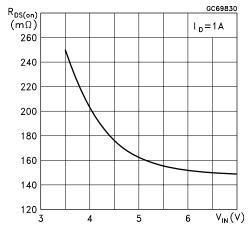
Static Drain-Source On Resistance

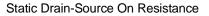


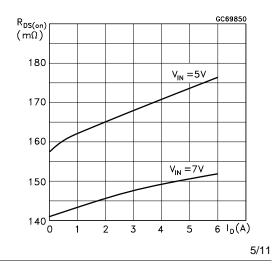
Derating Curve



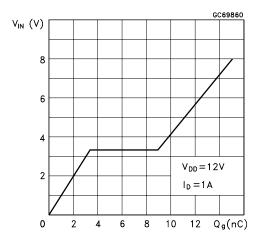


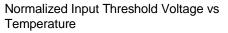


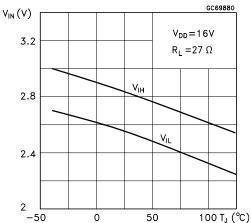




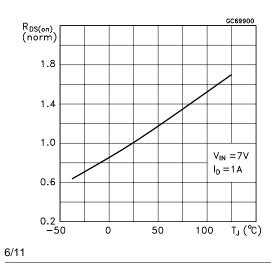
Input Charge vs Input Voltage



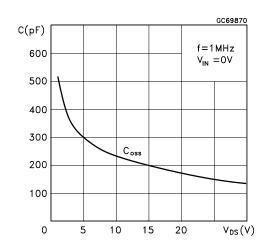




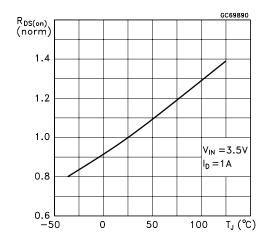


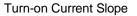


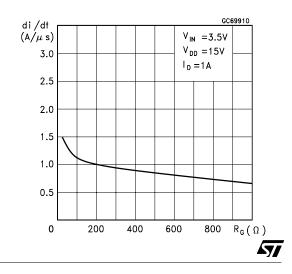
Capacitance Variations



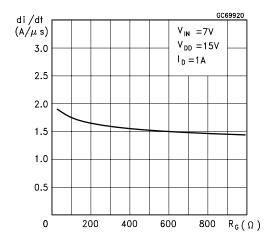
Normalized On Resistance vs Temperature



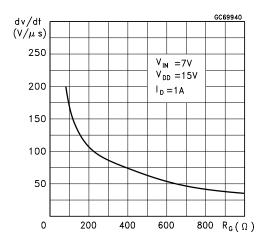




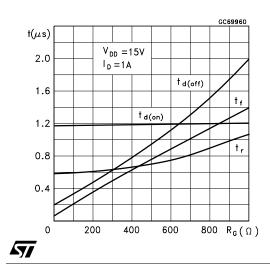
Turn-on Current Slope



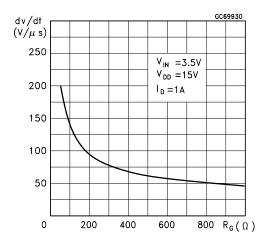
Turn-off Drain-Source Voltage Slope



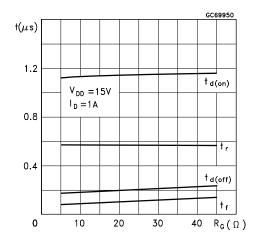




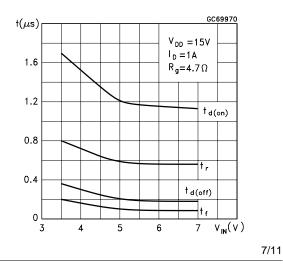
Turn-off Drain-Source Voltage Slope

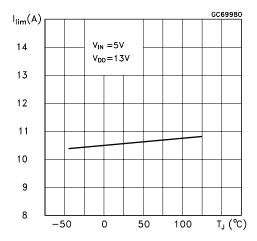


Switching Time Resistive Load



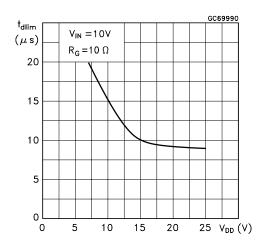






Current Limit vs Junction Temperature

Step Response Current Limit



Source Drain Diode Voltage vs Junction Temperature

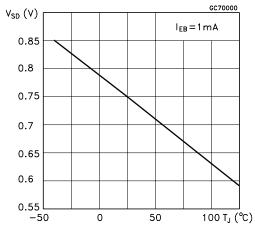




Fig. 1: Unclamped Inductive Load Test Circuits

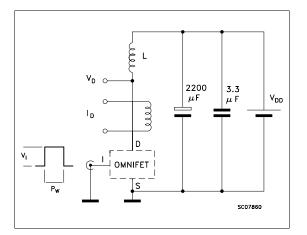


Fig. 3: Switching Times Test Circuits For Resistive Load

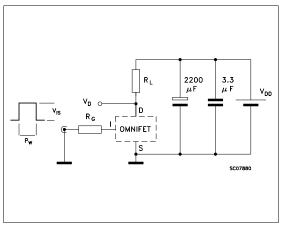


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

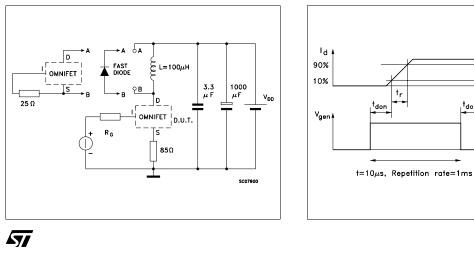


Fig. 2: Unclamped Inductive Waveforms

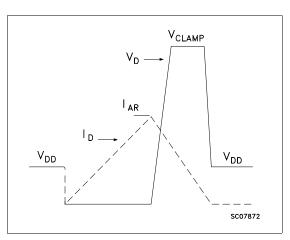


Fig. 4: Input Charge Test Circuit

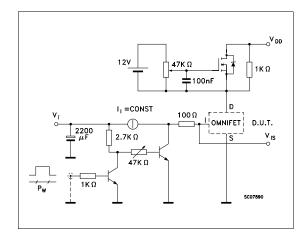
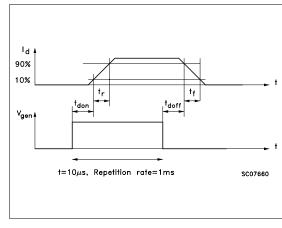


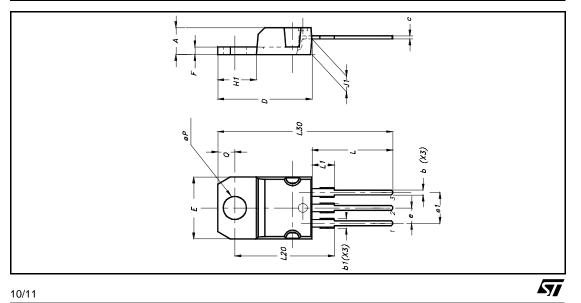
Fig. 6: Waveforms



VNP10N06

		mm.	
DIM.	MIN.	ТҮР	MAX.
А	4.40		4.60
b	0.61		0.88
b1	1.15		1.70
с	0.49		0.70
D	15.25		15.75
E	10		10.40
е	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95
Package Weight		1.9Gr. (Typ.)	

TO-220 MECHANICAL DATA



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